

N-Channel 250 V (D-S) MOSFET

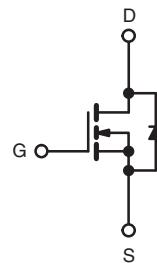
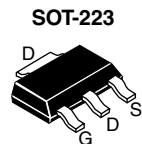
PRODUCT SUMMARY		
V_{DS} (V)	250	
$R_{DS(on)}$ (Ω)	$V_{GS} = 10\text{ V}$	2.0
Q_g (Max.) (nC)	8.2	
Q_{gs} (nC)	1.8	
Q_{gd} (nC)	4.5	
Configuration	Single	

FEATURES

- Surface mount
- Available in tape and reel
- Dynamic dV/dt rating
- Repetitive avalanche rated
- Fast switching
- Ease of paralleling
- Simple drive requirements



RoHS
COMPLIANT
HALOGEN
FREE
Available



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V_{DS}	250	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current	V_{GS} at 10 V	I_D	$T_C = 25\text{ }^\circ\text{C}$	0.79
			$T_C = 100\text{ }^\circ\text{C}$	0.50
Pulsed Drain Current ^a		I_{DM}	6.3	A
Linear Derating Factor			0.025	
Linear Derating Factor (PCB Mount) ^e			0.017	
Single Pulse Avalanche Energy ^b		E_{AS}	50	mJ
Repetitive Avalanche Current ^a		I_{AR}	0.79	A
Repetitive Avalanche Energy ^a		E_{AR}	0.31	mJ
Maximum Power Dissipation		P_D	$T_C = 25\text{ }^\circ\text{C}$	3.1
Maximum Power Dissipation (PCB Mount) ^e			$T_A = 25\text{ }^\circ\text{C}$	2.0
Peak Diode Recovery dV/dt ^c		dV/dt	4.8	V/ns
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to +150	$^\circ\text{C}$
Soldering Recommendations (Peak Temperature) ^d		for 10 s	300	

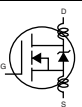
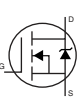
Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 50\text{ V}$, starting $T_J = 25\text{ }^\circ\text{C}$, $L = 128\text{ mH}$, $R_g = 25\text{ }\Omega$, $I_{AS} = 0.79\text{ A}$ (see fig. 12).
- $I_{SD} \leq 2.7\text{ A}$, $di/dt \leq 65\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DS}$, $T_J \leq 150\text{ }^\circ\text{C}$.
- 1.6 mm from case.
- When mounted on 1" square PCB (FR-4 or G-10 material).

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient (PCB Mount) ^a	R _{thJA}	-	-	60	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	-	-	40	

Note

a. When mounted on 1" square PCB (FR-4 or G-10 material).

SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNIT
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA		250	-	- V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = 1 mA		-	0.39	- V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		2.0	-	4.0 V
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100 nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 250 V, V _{GS} = 0 V		-	-	25 μA
		V _{DS} = 200 V, V _{GS} = 0 V, T _J = 125 °C		-	-	250 μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 0.47 A ^b	-	2.0	- Ω
Forward Transconductance	g _{fs}	V _{DS} = 50 V, I _D = 0.47 A		0.50	-	- S
Dynamic						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1.0 MHz, see fig. 5		-	140	- pF
Output Capacitance	C _{oss}			-	42	-
Reverse Transfer Capacitance	C _{rss}			-	9.6	-
Total Gate Charge	Q _g	V _{GS} = 10 V	I _D = 2.7 A, V _{DS} = 200 V, see fig. 6 and 13 ^b	-	-	8.2 nC
Gate-Source Charge	Q _{gs}			-	-	1.8
Gate-Drain Charge	Q _{gd}			-	-	4.5
Turn-On Delay Time	t _{d(on)}	V _{DD} = 125 V, I _D = 2.7 A, R _g = 24 Ω, R _D = 45 Ω, see fig. 10 ^b		-	7.0	- ns
Rise Time	t _r			-	7.6	-
Turn-Off Delay Time	t _{d(off)}			-	16	-
Fall Time	t _f			-	7.0	-
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact 		-	4.0	- nH
Internal Source Inductance	L _S			-	6.0	-
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	0.79 A
Pulsed Diode Forward Current ^a	I _{SM}			-	-	6.3
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S = 0.79 A, V _{GS} = 0 V ^b		-	-	2.0 V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = 2.7 A, dI/dt = 100 A/μs ^b		-	190	390 ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	0.64	1.3 μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)				

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width ≤ 300 μs; duty cycle ≤ 2 %.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

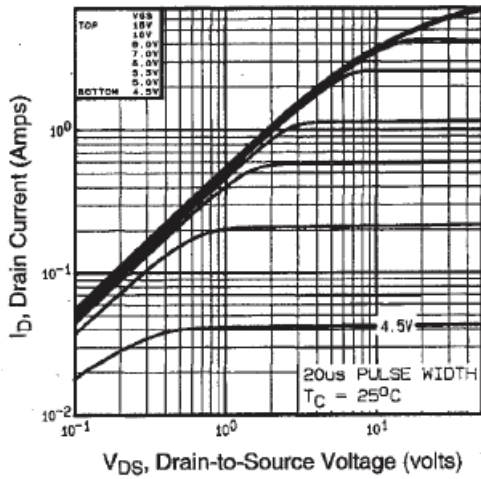


Fig. 1 - Typical Output Characteristics

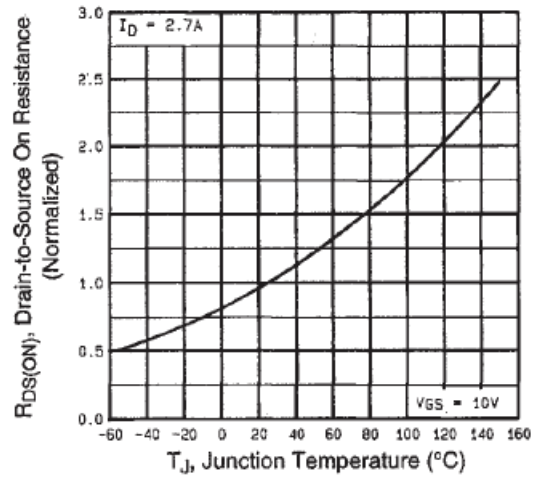


Fig. 4 - Normalized On-Resistance vs. Temperature

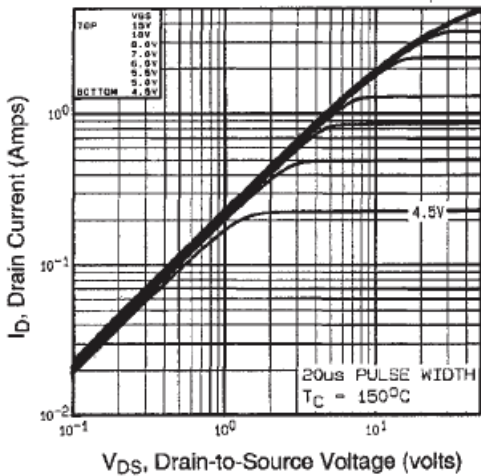


Fig. 2 - Typical Output Characteristics

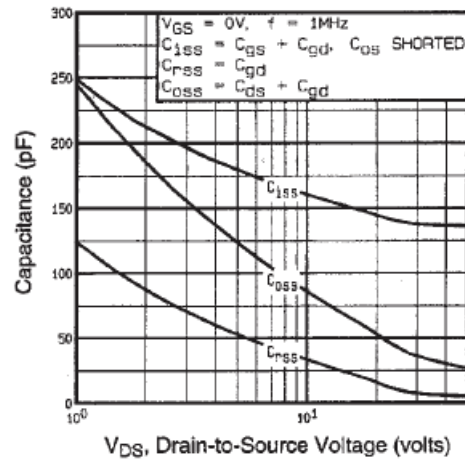


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

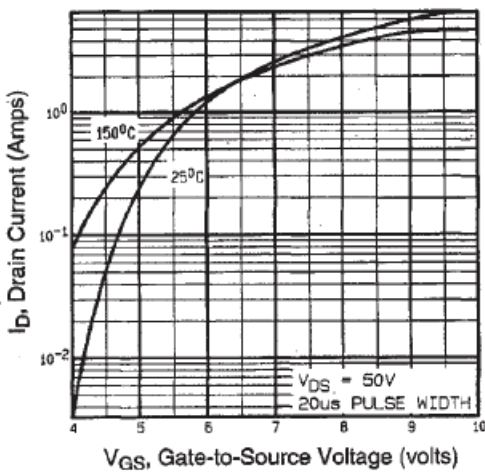


Fig. 3 - Typical Transfer Characteristics

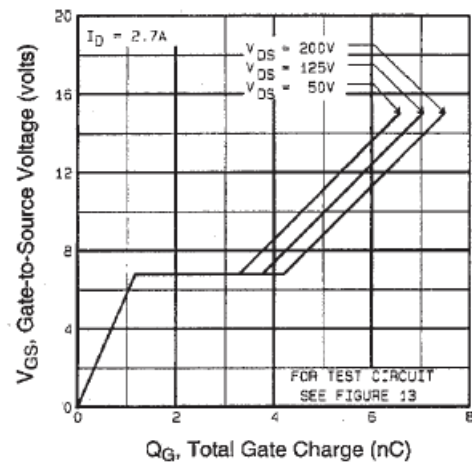


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

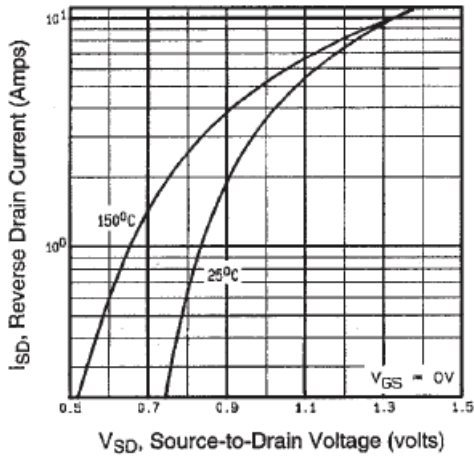


Fig. 7 - Typical Source-Drain Diode Forward Voltage

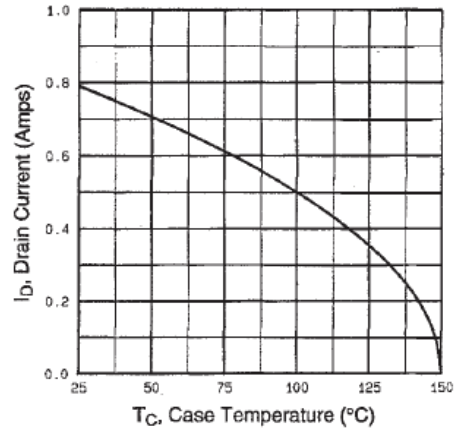


Fig. 9 - Maximum Drain Current vs. Case Temperature

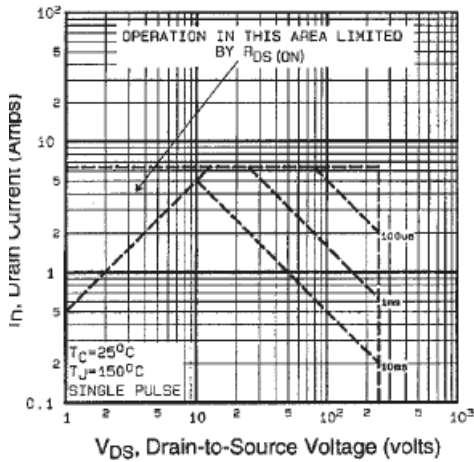


Fig. 8 - Maximum Safe Operating Area

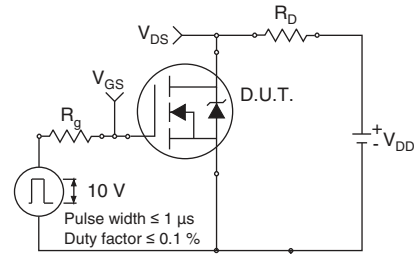


Fig. 10a - Switching Time Test Circuit

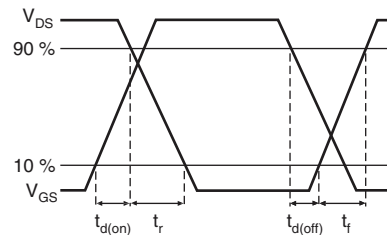


Fig. 10b - Switching Time Waveforms

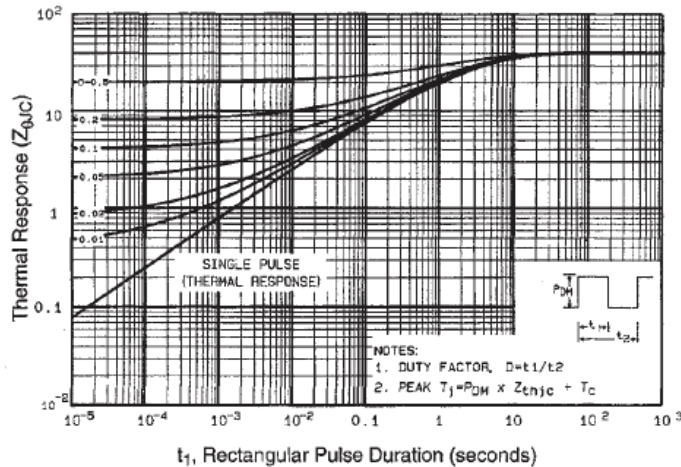


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

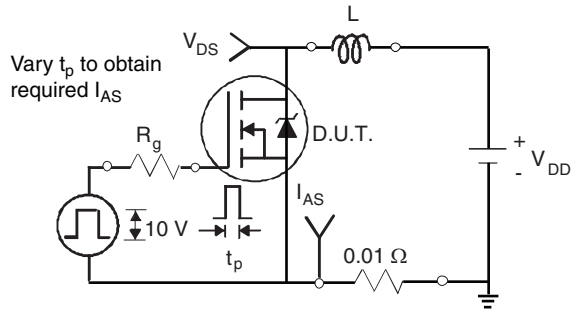


Fig. 12a - Unclamped Inductive Test Circuit

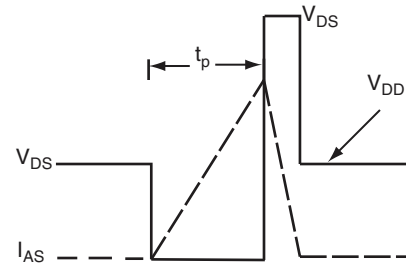


Fig. 12b - Unclamped Inductive Waveforms

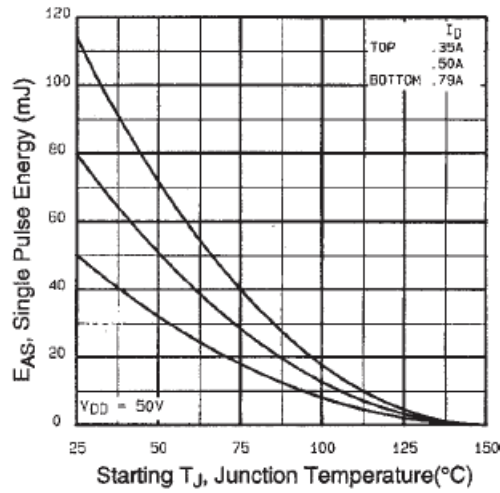


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

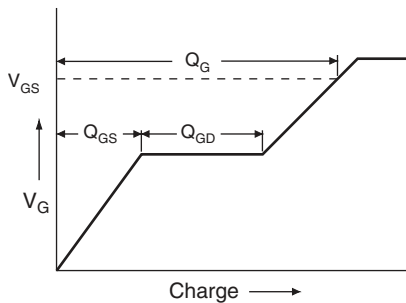


Fig. 13a - Basic Gate Charge Waveform

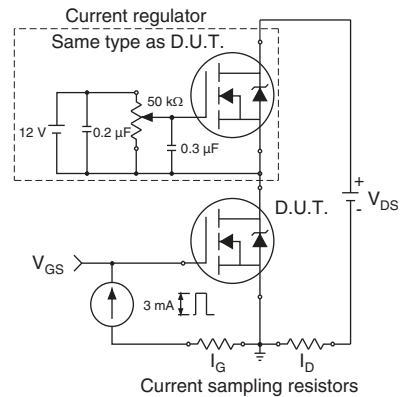
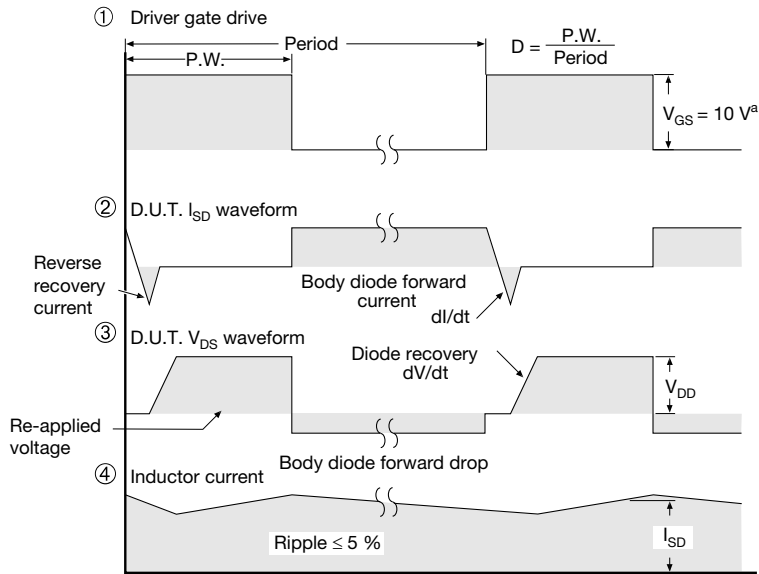
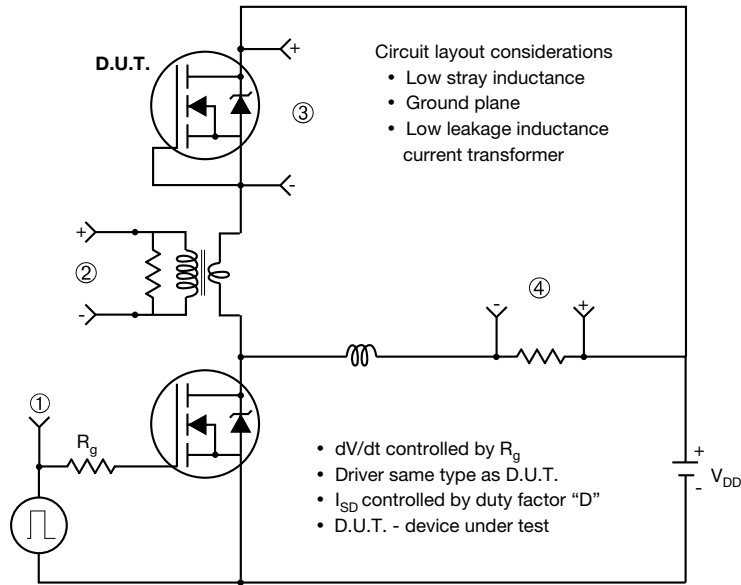


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit

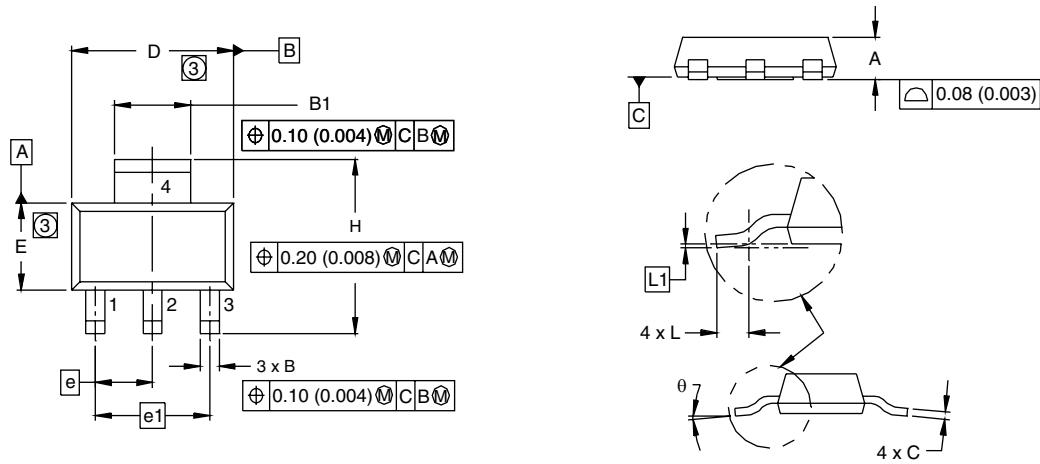


Note

a. $V_{GS} = 5 V$ for logic level devices

Fig.14 - For N-Channel

SOT-223 (HIGH VOLTAGE)



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	1.55	1.80	0.061	0.071
B	0.65	0.85	0.026	0.033
B1	2.95	3.15	0.116	0.124
C	0.25	0.35	0.010	0.014
D	6.30	6.70	0.248	0.264
E	3.30	3.70	0.130	0.146
e	2.30 BSC		0.0905 BSC	
e1	4.60 BSC		0.181 BSC	
H	6.71	7.29	0.264	0.287
L	0.91	-	0.036	-
L1	0.061 BSC		0.0024 BSC	
theta	-	10'	-	10'

ECN: S-82109-Rev. A, 15-Sep-08
DWG: 5969

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension do not include mold flash.
4. Outline conforms to JEDEC outline TO-261AA.

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